

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	10084	29/592.1,605,830-832,842,846,854.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 11:42
S2	150	microstimulator	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:03
S3	0	S1 and S2	USPAT; JPO; DERWENT	OR	ON	2005/10/20 11:42
S4	45	((("5193539") or ("5193540") or ("5312439") or ("5350980") or ("5405367") or ("5750926") or ("5999848") or ("6051017") or ("6061596") or ("6164284") or ("6175764") or ("6181965") or ("6185452") or ("6185455") or ("6208894") or ("6214032") or ("6232562") or ("6259937") or ("6315721") or ("6340839") or ("6516808") or ("6539253") or ("6553263") or ("6567703"))).PN.	USPAT; USOCR; JPO; DERWENT	OR	OFF	2005/10/20 11:56
S5	5412	174/52.1,255,260,261.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 11:50
S6	1638	607/1-3,46,48-52,59-61.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:01
S7	353	600/302,554,377.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 11:57
S8	116	128/877.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 11:57
S9	0	S2 and S5	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:01
S10	19	S2 and S4	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:01
S11	52	S2 and S6	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:07
S12	0	S2 and S7	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:02
S13	14	S10 and S11	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:02

S14	3721	circuit with substrate with trace	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:08
S15	0	S2 and S14	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:03
S16	19000	microstimulator or stimulator	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:03
S17	10	S1 and S16	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:05
S18	0	S14 and S17	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:03
S19	164	S1 and S14	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:04
S20	0	S5 and S9	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:04
S21	32	S5 and S19	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:04
S22	738	S6 and S16	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:05
S23	1	S14 and S22	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:06
S24	1	S5 and S16	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:06
S25	111	S7 and S16	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:07
S26	8	S22 and S25	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:07
S27	0	S11 and S14	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:08
S28	1	S11 and (circuit with trace)	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:09

S29	56	("3617646"   "3682160"   "3995234"   "4218772"   "4245178"   "4321706"   "4539531"   "4553110"   "4553882"   "4596022"   "4743789"   "4814962"   "4833427"   "4916380"   "5053723"   "5193539"   "5193540"   "5324316"   "5405367"   "5414741"   "5438302"   "5486794"   "5506547"   "5543754"   "5643332"   "5666279"   "5697076"   "5766232"   "5798616"   "5838203"   "5872703"   "6016257"   "6046650"   "6051017"   "6064277"   "6073050"   "6215365"   "6225873"   "6229406"   "6239665"   "6255913"   "6268777"   "6275539"   "6456169"   "6462964"   "6469587"   "6509805"   "6538521"   "6539253"   "6545554"   "6553263"   "6593822"   "6593825"   "6606006"   "6614288"   "6621365").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/20 12:08
S30	6	S2 and S29	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:10
S31	0	S30 and (circuit with trace)	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:09
S32	8	He-Tom-Xiaohai.in. or Haller-Matthew-I.in. or Parramon-Jordi.in. or Marnfeldt-Goran-N.in.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:11
S33	0	S2 and S8	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:11
S34	54423	(substrate with pad)	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:06
S37	7712	(integrated adj circuit) with ((conductive or metal) adj layer)	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:09
S38	11132	connect\$3 with substrate with (integrated adj circuit)	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:08

S39	266	S34 and S37 and S38	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:08
S40	453	((conductive or metal) adj layer) with trace with pad	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:10
S41	18	S39 and S40	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:09
S42	39927	((insulat\$3 or dielectric) adj layer) with ((conductive or metal) adj layer)	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:10
S43	11	S41 and S42	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:27
S44	8400	257/723,724,737,738,782-786. ccls.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:28
S45	10	S37 and S38 and S40 and S44	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:30
S46	4377	361/735,794,683,810,777,778, 792.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:30
S47	2	S37 and S38 and S40 and S46	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:34
S48	15657131	JP 0616919-\$.did.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:35
S49	0	JP-0616919-\$.did.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:35
S50	0	JP-40616919-\$.did.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:35
S51	0	JP-616919-\$.did.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:35
S52	444074	(integrated adj circuit) or (printed adj circiut)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:16
S53	1	trace with (mount\$3 adj pad) with (interconnect adj pad)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:06
S54	8250	trace with pad	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:06

S55	642	((integrated adj circuit) or (printed adj circuit)) with (trace with pad)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:17
S56	7	(mount\$3 adj pad) with (interconnect adj pad)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:07
S57	0	(mount\$3 adj pad) with (interconnect adj pad) with (conductive adj layer)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:07
S58	642	((integrated adj circuit) or (printed adj circuit)) with (trace with pad\$1)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:19
S59	0	((integrated adj circuit) with (printed adj circuit)) with (trace with pad\$1)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:19
S60	74	((integrated adj circuit) with (printed adj circuit)) with (trace with pad\$1)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:20
S61	7	((integrated adj circuit) with (printed adj circuit)) with (trace with pad\$1) same (insulat\$3 or dielectric)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:53
S62	642	(integrated adj circuit) with (trace with pad\$1)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:32
S63	0	(integrated adj circuit) near (printed adj circuit)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:35
S64	1739	(integrated adj circuit) near (printed adj circuit)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:35
S65	22	S62 and S64	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:35
S66	13	("4907067"   "5223741"   "5229727"   "5270673"   "5389904"   "5753972"   "5900312"   "6124636"   "6147389"   "6172412"   "6248959"   "6271579"   "6509531").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 07:50
S67	1115	(printed adj circuit) with (trace with pad\$1)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:54
S68	31	S64 and S67	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:54



S69	0	trace near pad near insualtion	USPAT; JPO; DERWENT	OR	ON	2005/10/24 08:56
S70	11	trace near pad near insulat\$3	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:00
S71	1	(US-6511865-\$).did.	USPAT	OR	ON	2005/10/24 09:00
S72	1	S71 and insulat\$3	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:00
S73	250	process\$3 near (integrated adj circuit) near wafer	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:29
S74	0	post near process\$3 near (integrated adj circuit) near wafer	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:16
S75	26226	(post adj process\$3)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:27
S76	2	S73 and S75	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:24
S77	5	("5732209"   "5926027"   "6032268"   "6162652"   "6400173").PN..	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 09:26
S78	0	S75 and S77	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 09:26
S79	6	(post adj process\$3) near IC	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:27
S80	0	(post adj process\$3) near (integrated adj circuit) near wafer	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:29
S81	9	(post adj process\$3) with ((integrated adj circuit) near wafer)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:31
S82	8	(post adj process\$3) near (integrated adj circuit)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:35
S83	133	(post adj process\$3) with (integrated adj circuit)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:35
S84	0	(post adj process\$3) with (integrated adj circuit) with web	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:36

S85	23	(post adj process\$3) with (integrated adj circuit) with wafer	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:36
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## » Key

IEEE JNL IEEE Journal or Magazine

IEEE JNL IEE Journal or Magazine

IEEE CNF IEEE Conference Proceeding

IEEE CNF IEE Conference Proceeding

IEEE STD IEEE Standard

☐ 1. RF telemetry powering and control of hermetically sealed integrated sensors and actuatorsAkin, T.; Ziaie, B.; Najafi, K.;  
Solid-State Sensor and Actuator Workshop, 1990. 4th Technical Digest., IEEE  
4-7 June 1990 Page(s):145 - 148  
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